

**INFORMATION DISCLOSURE STATEMENT**

Applicant : Jiang et al.
App. No. : 10/634,134
Filed : August 4, 2003
For : METHOD FOR ELECTROLESS PLATING A CONTACT PAD
Examiner : Unknown
Group Art Unit : Unknown

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Dear Sir:

Enclosed is form PTO-1449 listing 41 references. These references include references that are of record in U.S. Patent Application No. 09/256,548, filed February 24, 1999, now issued as U.S. Patent No. 6,303,500, issued October 16, 2001, which is the parent of this continuation application. Also enclosed are references that are of record in related U.S. Patent Application No. 09/854,292, filed May 9, 2001, now issued as U.S. Patent No. 6,630,400, issued October 7, 2003. Copies of the references are not submitted pursuant to 37 C.F.R. § 1.98(d).

This Information Disclosure Statement is being filed within three months of the filing date of this application and no fee is required in accordance with 37 C.F.R. § 1.97(b)(1), (b)(2), or (b)(4).

Respectfully submitted,

KNOBBE, MARTENS, OLSON & BEAR, LLP

Dated: 10/28/03

By: Bruce S. Itchkawitz

Bruce S. Itchkawitz
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Attorney of Record
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O P E JUL 31 2003 U.S. DEPARTMENT OF COMMERCE PATENT AND TRADEMARK OFFICE INFORMATION DISCLOSURE STATEMENT BY APPLICANT (USE SEVERAL SHEETS IF NECESSARY)		ATTY. DOCKET NO. MICRON.084C1C1	APPLICATION NO. 10/634,134
APPLICANT Jiang et al.			
FILING DATE August 4, 2003		GROUP Unknown	

U.S. PATENT DOCUMENTS

EXAMINER INITIAL	DOCUMENT NUMBER	DATE	NAME	CLASS	SUBCLASS	FILING DATE (IF APPROPRIATE)
1.	781,230	01/31/05	Rodman			
2.	2,935,420	05/03/60	Linden			
3.	3,339,526	9/05/67	Bradley et al.			
4.	3,839,037	10/1/74	Fromson			
5.	3,923,541	12/2/75	Healy			
6.	3,930,465	01/06/76	Schuerer			
7.	3,990,926	11/9/76	Konicek			
8.	4,113,899	9/12/78	Henry et al.			
9.	4,282,271	8/4/81	Feldstein			
10.	4,364,975	12/82	Cork et al.			
11.	4,474,311	10/02/84	Petrecca			
12.	4,603,656	08/05/86	Jaye, Jr.			
13.	4,762,601	9/9/88	Krulik et al.			
14.	4,772,496	9/20/88	Maeda et al.			
15.	4,913,082	4/3/90	Silbermann et al.			
16.	4,938,850	7/3/90	Rothschild et al.			
17.	5,028,454	7/2/91	Lytle et al.			
18.	5,118,362	7/2/92	St. Angelo et al.			
19.	5,194,313	3/16/93	Hupe et al.			
20.	5,206,052	4/27/93	Nakaso et al.			
21.	5,262,041	11/16/93	Gulla			
22.	5,342,501	08/94	Okabayashi			
23.	5,441,629	08/95	Kosaki			
24.	5,456,819	10/10/95	Lashmore et al.			
25.	5,492,863	2/20/96	Higgins, III			
26.	5,500,106	3/19/96	Goldberg			
27.	5,512,131	04/96	Kumar et al.			

EXAMINER	DATE CONSIDERED
*EXAMINER: INITIAL IF CITATION CONSIDERED, WHETHER OR NOT CITATION IS IN CONFORMANCE WITH MPEP 609; DRAW LINE THROUGH CITATION IF NOT IN CONFORMANCE AND NOT CONSIDERED, INCLUDE COPY OF THIS FORM WITH NEXT COMMUNICATION TO APPLICANT.	

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U.S. PATENT DOCUMENTS

EXAMINER INITIAL	DOCUMENT NUMBER	DATE	NAME	CLASS	SUBCLASS	FILING DATE (IF APPROPRIATE)
28.	5,583,073	12/10/96	Lin et al.			
29.	5,603,849	2/18/97	Li			
30.	5,618,634	4/8/97	Hosoda et al.			
31.	5,725,807	03/98	Thorn et al.			
32.	5,810,940	9/22/98	Fukazawa et al.			
33.	5,897,368	04/99	Cole, Jr. et al.			
34.	5,911,865	6/15/99	Yih			
35.	5,925,931	7/20/99	Yamamoto			

EXAMINER INITIAL	OTHER DOCUMENTS (INCLUDING AUTHOR, TITLE, DATE, PERTINENT PAGES, ETC.)	
36.	K. Baudrand, J. Bengston, "Electroless Plating Processes - Developing Technologies for Electroless Nickel, Palladium, and Gold," Metal Finishing, Sept. 1995, pp.55-57.	
37.	W.J. Hawk, "Electroless Palladium for Electronics," Metal Finishing, March 1986, pp.11-12.	
38.	J.K. Lim, J.S. Russo, E. Antonier, "Electroplated Palladium Coating As a Nickel Migration (Thermal) Barrier," Plating and Surface Finishing, March 1996, pp.64-67.	
39.	H. Nawafune, S. Mizumoto, M. Haga, E. Uchida, "Electroless Palladium Plating from an Ethylenediamine Complex Bath using Phosphite as a Reducing Agent," Transactions of the Institute of Metal Finishing, Vol. 74, #1, pp.21-24.	
40.	Rao, "Multilevel Interconnect Technology," Chapter: Manufacturing, p.141.	
41.	P. Steinmetz, S. Alperine, A. Friant-Costantini, P. Josso, "Electroless Deposition of Pure Nickel, Palladium and Platinum," Surface and Coatings Technology, 43/44 (1990), pp. 500-510.	

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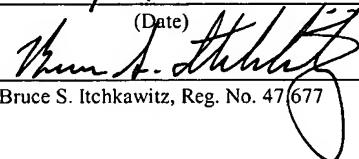
IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

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Examiner : Unknown
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I hereby certify that this correspondence and all marked attachments are being deposited with the United States Postal Service as first class mail in an envelope addressed to: Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450, on

10/28/03

(Date)


Bruce S. Itchkawitz, Reg. No. 47,677

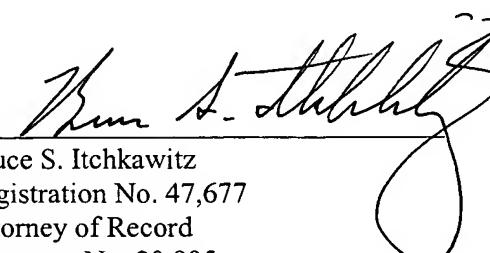
TRANSMITTAL LETTER

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Dear Sir:

Enclosed for filing in the above-identified application are:

- (X) An Information Disclosure Statement.
- (X) A PTO Form 1449 listing forty-one (41) references that are not enclosed.
- (X) The Commissioner is hereby authorized to charge any additional fees which may be required, or credit any overpayment, to Account No. 11-1410.
- (X) Return prepaid postcard.


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